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## Identification cards — Test methods —

### Part 6: Proximity cards

*Cartes d'identification — Méthodes d'essai —*

*Partie 6: Cartes de proximité*

**iTeh STANDARD PREVIEW**  
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## Foreword

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The procedures used to develop this document and those intended for its further maintenance are described in the ISO/IEC Directives, Part 1. In particular the different approval criteria needed for the different types of document should be noted. This document was drafted in accordance with the editorial rules of the ISO/IEC Directives, Part 2 (see [www.iso.org/directives](http://www.iso.org/directives)).

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The committee responsible for this document is ISO/IEC JTC 1, *Information technology*, Subcommittee SC 17, *Cards and personal identification*.

This third edition cancels and replaces the second edition (ISO/IEC 10373-6:2011), which has been technically revised.

It also incorporates the Amendments ISO/IEC 10373-6:2011/Amd 1:2012, ISO/IEC 10373-6:2011/Amd 2:2012, ISO/IEC 10373-6:2011/Amd 3:2012, ISO/IEC 10373-6:2011/Amd 4:2012, and the Technical Corrigendum ISO/IEC 10373-6:2011/Cor 1:2013.

ISO/IEC 10373 consists of the following parts, under the general title *Identification cards — Test methods*:

- *Part 1: General characteristics*
- *Part 2: Cards with magnetic stripes*
- *Part 3: Integrated circuit cards with contacts and related interface devices*
- *Part 5: Optical memory cards*
- *Part 6: Proximity cards*
- *Part 7: Vicinity cards*
- *Part 8: USB-ICC*
- *Part 9: Optical memory cards — Holographic recording method*